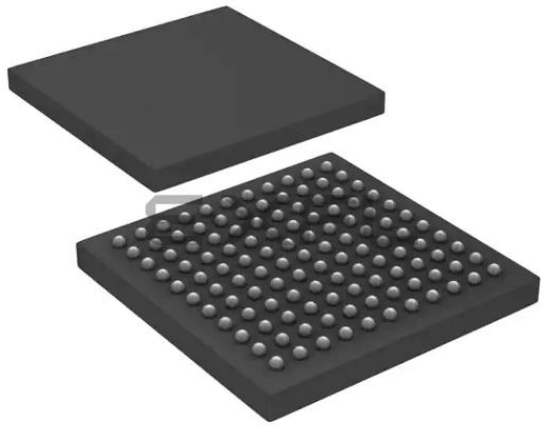
Microchip Technology - DSPIC33EP512MU810-I/BG Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	83
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mu810-i-bg

Pin Diagrams (Continued)

121-Pin TFBGA(1)

● = Pins are up to 5V tolerant

dsPIC33EP256MU810
dsPIC33EP512MU810

	1	2	3	4	5	6	7	8	9	10	11
A	RE4	RE3	RG13	RE0	RG0	RF1	VDD	NC	RD12	RD2	RD1
B	NC	RG15	RE2	RE1	RA7	RF0	VCAP	RD5	RD3	VSS	RC14
C	RE6	VDD	RG12	RG14	RA6	NC	RD7	RD4	NC	RC13	RD11
D	RC1	RE7	RE5	NC	NC	NC	RD6	RD13	RD0	NC	RD10
E	RC4	RC3	RG6	RC2	NC	RG1	NC	RA15	RD8	RD9	RA14
F	$\overline{MCLR}$	RG8	RG9	RG7	VSS	NC	NC	VDD	RC12	VSS	RC15
G	RE8	RE9	RA0	NC	VDD	VSS	VSS	NC	RA5	RA3	RA4
H	RB5	RB4	NC	NC	NC	VDD	NC	VBUS	VUSB3V3	RG2	RA2
J	RB3	RB2	RB7	AVDD	RB11	RA1	RB12	NC	NC	RF8	RG3
K	RB1	RB0	RA10	RB8	NC	RF12	RB14	VDD	RD15	RF3	RF2
L	RB6	RA9	AVSS	RB9	RB10	RF13	RB13	RB15	RD14	RF4	RF5

Note 1: Refer to Table 2 for full pin names.

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (Figure 4-2).

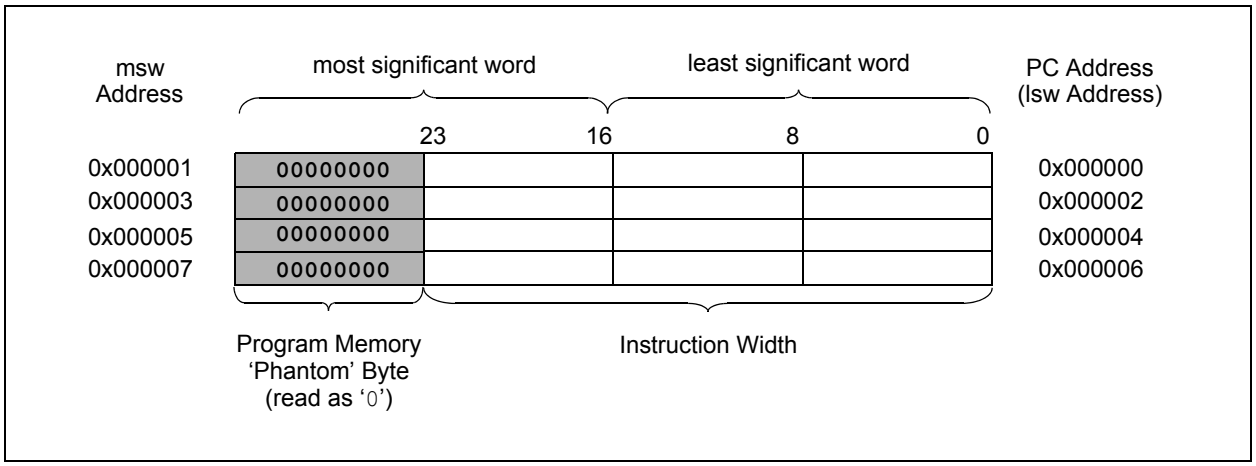
Program memory addresses are always word-aligned on the lower word and addresses are incremented or decremented by two during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All devices reserve the addresses between 0x00000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at address 0x000000 of the primary Flash memory or at address 0x7FFFFC of the auxiliary Flash memory, with the actual address for the start of code at address 0x000002 of the primary Flash memory or at address 0x7FFFFE of the auxiliary Flash memory. Reset Target Vector Select bit (RSTPRI) in the FPOR Configuration register controls whether primary or auxiliary Flash Reset location is used.

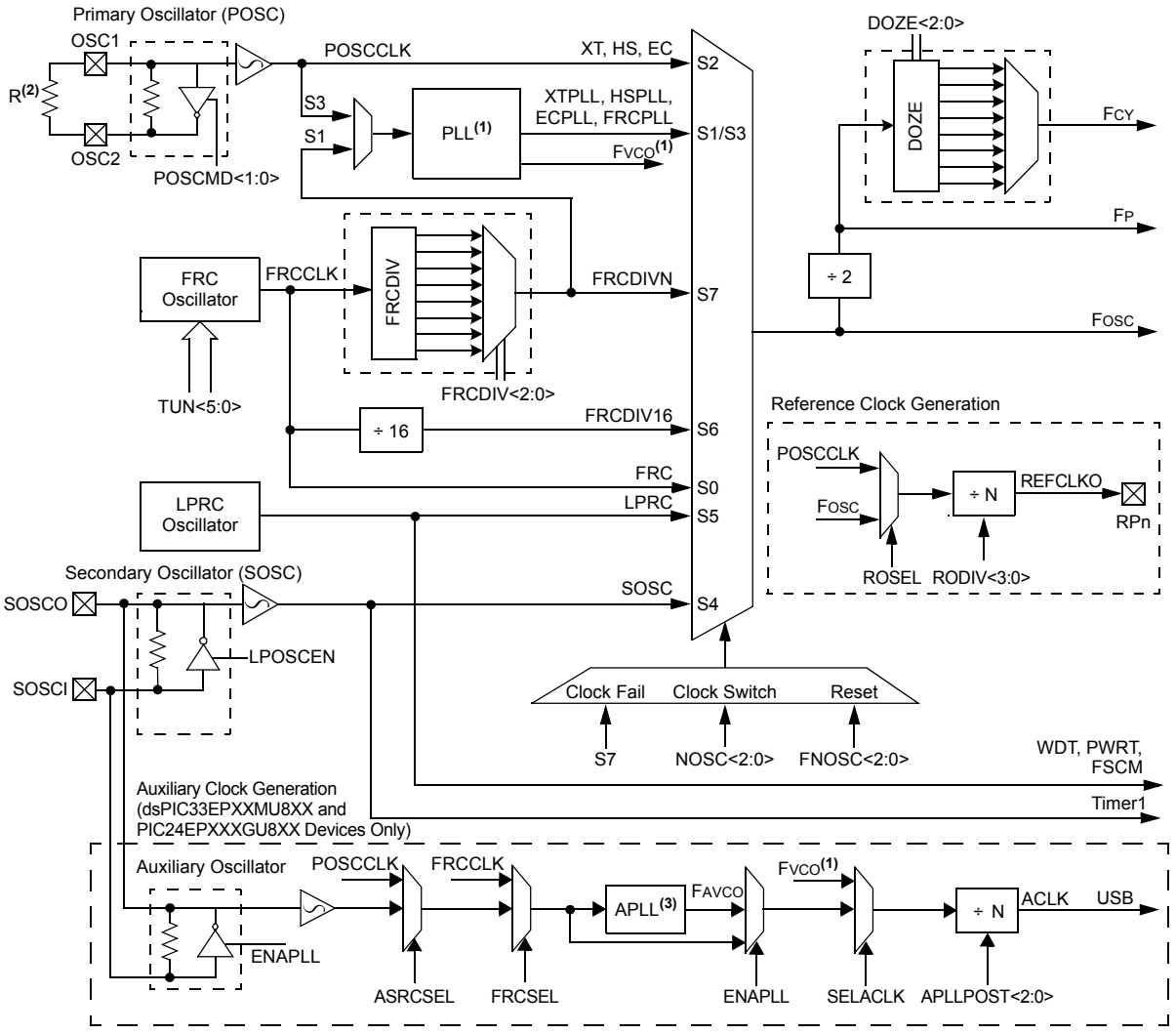
A more detailed discussion of the interrupt vector tables is provided in **Section 7.1 "Interrupt Vector Table"**.

FIGURE 4-2: PROGRAM MEMORY ORGANIZATION



NOTES:

FIGURE 9-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL and FVCO details.
2: If the oscillator is used with XT or HS modes, an external parallel resistor with the value of 1 MΩ must be connected.
3: See Figure 9-3 for APLL details.

REGISTER 11-30: RPINR30: PERIPHERAL PIN SELECT INPUT REGISTER 30

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SS3R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-0 **SS3R<6:0>:** Assign SPI3 Slave Select Input ($\overline{SS3}$) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 11-49: RPOR5: PERIPHERAL PIN SELECT OUTPUT REGISTER 5

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP84R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP82R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP84R<5:0>:** Peripheral Output Function is Assigned to RP84 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP82R<5:0>:** Peripheral Output Function is Assigned to RP82 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-50: RPOR6: PERIPHERAL PIN SELECT OUTPUT REGISTER 6

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP87R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP85R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP87R<5:0>:** Peripheral Output Function is Assigned to RP87 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP85R<5:0>:** Peripheral Output Function is Assigned to RP85 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^2C slave)
Used in conjunction with the SCLREL bit.
1 = Enables software or receives clock stretching
0 = Disables software or receives clock stretching

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^2C master, applicable during master receive)
Value that is transmitted when the software initiates an Acknowledge sequence.
1 = Sends NACK during Acknowledge
0 = Sends ACK during Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit (when operating as I^2C master, applicable during master receive)
1 = Initiates Acknowledge sequence on SDAx and SCLx pins and transmits the ACKDT data bit. Hardware is clear at the end of a master Acknowledge sequence.
0 = Acknowledge sequence is not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^2C master)
1 = Enables Receive mode for I^2C. Hardware is clear at the end of the eighth bit of a master receive data byte.
0 = Receive sequence is not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^2C master)
1 = Initiates Stop condition on SDAx and SCLx pins. Hardware is clear at the end of a master Stop sequence.
0 = Stop condition is not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^2C master)
1 = Initiates Repeated Start condition on SDAx and SCLx pins. Hardware is clear at the end of a master Repeated Start sequence.
0 = Repeated Start condition is not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^2C master)
1 = Initiates Start condition on SDAx and SCLx pins. Hardware is clear at the end of a master Start sequence.
0 = Start condition is not in progress

Note 1: When performing master operations, ensure that the IPMIEN bit is '0'.

REGISTER 21-22: CxRXFUL1: ECANx RECEIVE BUFFER FULL REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<15:0>:** Receive Buffer n Full bits

1 = Buffer is full (set by module)

0 = Buffer is empty (cleared by user software)

REGISTER 21-23: CxRXFUL2: ECANx RECEIVE BUFFER FULL REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<31:16>:** Receive Buffer n Full bits

1 = Buffer is full (set by module)

0 = Buffer is empty (cleared by user software)

REGISTER 21-24: CxRXOVF1: ECANx RECEIVE BUFFER OVERFLOW REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXOVF<15:0>:** Receive Buffer n Overflow bits
1 = Module attempted to write to a full buffer (set by module)
0 = No overflow condition (cleared by user software)

REGISTER 21-25: CxRXOVF2: ECANx RECEIVE BUFFER OVERFLOW REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXOVF<31:16>:** Receive Buffer n Overflow bits
1 = Module attempted to write to a full buffer (set by module)
0 = No overflow condition (cleared by user software)

22.4 USB Control Registers

REGISTER 22-1: UxOTGSTAT: USB OTG STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R-0, HSC	U-0	R-0, HSC	U-0	R-0, HSC	R-0, HSC	U-0	R-0, HSC
ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD
bit 7							bit 0

Legend:	U = Unimplemented bit, read as '0'		
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **ID:** ID Pin State Indicator bit
1 = No cable is attached or a Type B plug has been plugged into the USB receptacle
0 = A Type A plug has been plugged into the USB receptacle

bit 6 **Unimplemented:** Read as '0'

bit 5 **LSTATE:** Line State Stable Indicator bit
1 = The USB line state (as defined by SE0 and JSTATE) has been stable for the previous 1 ms
0 = The USB line state has NOT been stable for the previous 1 ms

bit 4 **Unimplemented:** Read as '0'

bit 3 **SESVD:** Session Valid Indicator bit
1 = The VBUS voltage is above VA_SESS_VLD (as defined in the USB OTG Specification) on the A or B device
0 = The VBUS voltage is below VA_SESS_VLD on the A or B device

bit 2 **SESEND:** B-Session End Indicator bit
1 = The VBUS voltage is below VB_SESS_END (as defined in the USB OTG Specification) on the B device
0 = The VBUS voltage is above VB_SESS_END on the B device

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVD:** A-VBUS Valid Indicator bit
1 = The VBUS voltage is above VA_VBUS_VLD (as defined in the USB OTG Specification) on the A device
0 = The VBUS voltage is below VA_VBUS_VLD on the A device

REGISTER 22-20: UxEIE: USB ERROR INTERRUPT ENABLE REGISTER (DEVICE MODE)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BTSEE	BUSACCEE	DMAEE	BTOEE	DFN8EE	CRC16EE	CRC5EE	PIDEE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **BTSEE:** Bit Stuff Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 6 **BUSACCEE:** Bus Access Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 5 **DMAEE:** DMA Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 4 **BTOEE:** Bus Turnaround Time-out Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 3 **DFN8EE:** Data Field Size Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 2 **CRC16EE:** CRC16 Failure Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 1 **CRC5EE:** CRC5 Host Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 0 **PIDEE:** PID Check Failure Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

NOTES:

REGISTER 26-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1) (CONTINUED)

bit 7-0 **CAL<7:0>:** RTCC Drift Calibration bits

01111111 = Maximum positive adjustment; adds 508 RTCC clock pulses every one minute
•
•
•
00000001 = Minimum positive adjustment; adds four RTCC clock pulses every one minute
00000000 = No adjustment
11111111 = Minimum negative adjustment; subtracts four RTCC clock pulses every one minute
•
•
•
10000000 = Maximum negative adjustment; subtracts 512 RTCC clock pulses every one minute

Note 1: The RCFGCAL register is only affected by a POR.

2: A write to the RTCEN bit is only allowed when RTCWREN = 1.

3: This bit is read-only. It is cleared when the lower half of the MINSEC register is written.

32.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to V_{SS} **(3)** ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 3.0V$ **(3)** ..... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to Vss when $V_{DD} < 3.0V$ **(3)** ..... -0.3V to 3.6V
Voltage on D+ OR D- pin with respect to V_{USB3V3} ..... -0.3V to (V_{USB3V3} +0.3V)
Voltage on V_{BUS} with respect to V_{SS} ..... -0.3V to +5.5V
Maximum current out of V_{SS} pin ..... 320 mA
Maximum current into V_{DD} pin **(2)** ..... 320 mA
Maximum current sourced/sunk by any 4x I/O pin **(4)** ..... 15 mA
Maximum current sourced/sunk by any 8x I/O pin **(4)** ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports **(2)** ..... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 32-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

4: Characterized but not tested.

TABLE 32-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 4x Sink Driver Pins – All I/O Pins except OSC2 and SOSCO	—	—	0.4	V	IOL ≤ 10 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 8x Sink Driver Pins – OSC2 and SOSCO	—	—	0.4	V	IOL ≤ 15 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins: 4x Sink Driver Pins – All I/O Pins except OSC2 and SOSCO	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Sink Driver Pins – OSC2 and SOSCO	2.4	—	—	V	IOH ≥ -15 mA, VDD = 3.3V
DO20A	VOH1	**Output High Voltage** I/O Pins: 4x Sink Driver Pins – All I/O Pins except OSC2 and SOSCO	1.5(1)	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -12 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -7 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Sink Driver Pins – OSC2 and SOSCO	1.5(1)	—	—	V	IOH ≥ -22 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -18 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -10 mA, VDD = 3.3V

Note 1: Parameters are characterized, but not tested.

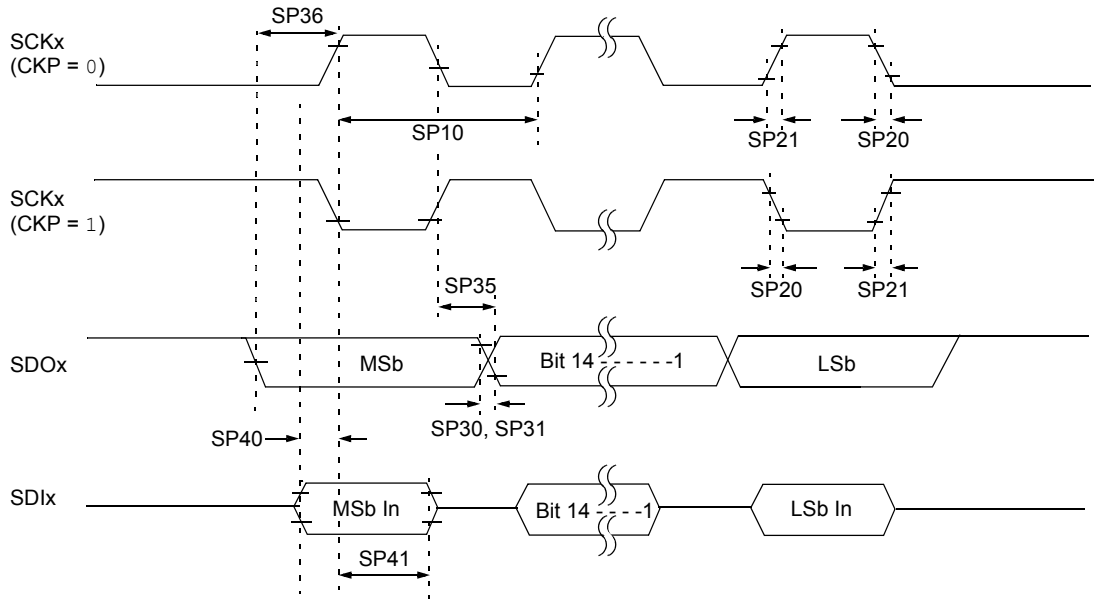
TABLE 32-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(2) (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.(1)**	**Typ.**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD Transition High-to-Low	2.7	—	2.9	V	VDD

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules: ADC, Comparator and DAC will have degraded performance. Device functionality is tested but not characterized.

FIGURE 32-25: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 32-1 for load conditions.

TABLE 32-43: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	10	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 32-58: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (see Note 4) (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	76	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	12 TAD	—	—	
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	Using sequential sampling
AD57	TSAMP	Sample Time	2 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(2)	2 TAD	—	3 TAD	—	Auto-Convert Trigger not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(2)	2 TAD	—	3 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(2)	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(2)	—	—	20	μs	See **Note 3**

Note 1: These parameters are characterized but not tested in manufacturing.

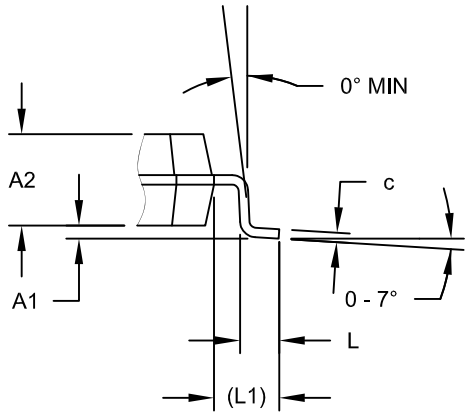
2: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

3: The tDPU parameter is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (ADxCON1<15>) = 1). During this time, the ADC result is indeterminate.

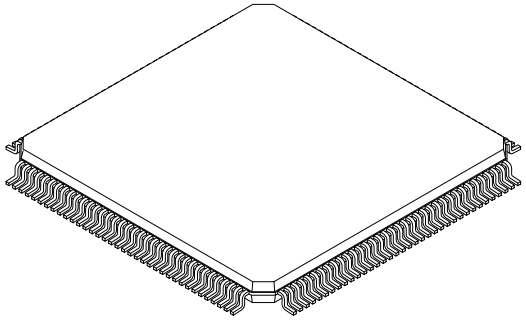
4: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules: ADC, Comparator and DAC will have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 32-11 for the minimum and maximum BOR values.

144-Lead Plastic Low Profile Quad Flatpack (PL) – 20x20x1.40 mm Body, with 2.00 mm Footprint [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		144	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.60
Molded Package Height	A2	1.35	1.40	1.45
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 (REF)	
Overall Width	E		22.00 BSC	
Overall Length	D		22.00 BSC	
Molded Body Width	E1		20.00 BSC	
Molded Body Length	D1		20.00 BSC	
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27

Notes:

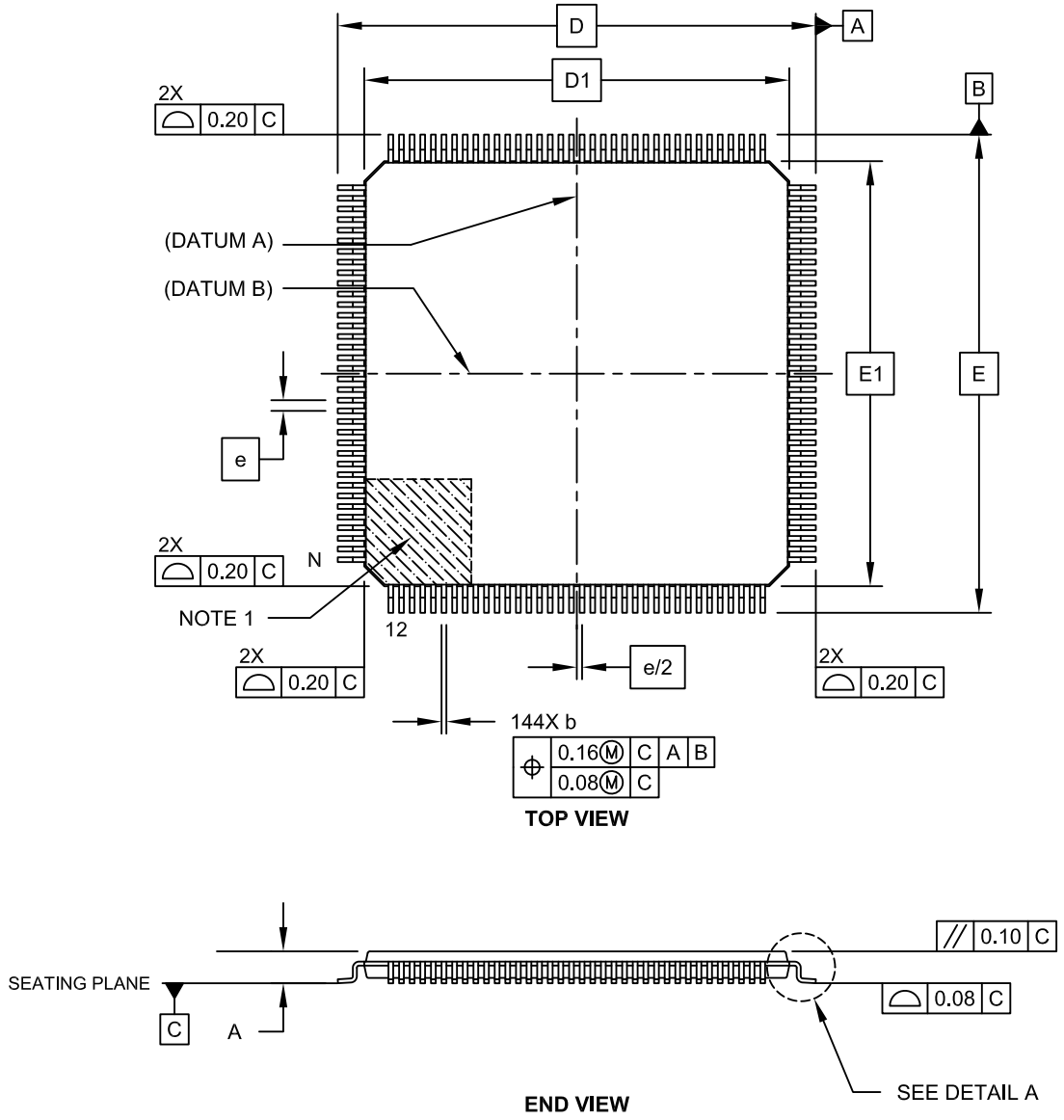
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-044B Sheet 2 of 2

144-Lead Plastic Thin Quad Flatpack (PH)-16x16x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-155B Sheet 1 of 2

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

TO: Technical Publications Manager
RE: Reader Response

Total Pages Sent _____

From: Name _____

Company _____

Address _____

City / State / ZIP / Country _____

Telephone: (_____) _____ - _____ FAX: (_____) _____ - _____

Application (optional):

Would you like a reply? ___Y ___N

Device: dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814

Literature Number: DS70616G

Questions:

1. What are the best features of this document?

2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this document easy to follow? If not, why?

4. What additions to the document do you think would enhance the structure and subject?

5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?